

Chipsmall Limited consists of a professional team with an average of over 10 year of expertise in the distribution of electronic components. Based in Hongkong, we have already established firm and mutual-benefit business relationships with customers from, Europe, America and south Asia, supplying obsolete and hard-to-find components to meet their specific needs.

With the principle of "Quality Parts, Customers Priority, Honest Operation, and Considerate Service", our business mainly focus on the distribution of electronic components. Line cards we deal with include Microchip, ALPS, ROHM, Xilinx, Pulse, ON, Everlight and Freescale. Main products comprise IC, Modules, Potentiometer, IC Socket, Relay, Connector. Our parts cover such applications as commercial, industrial, and automotives areas.

We are looking forward to setting up business relationship with you and hope to provide you with the best service and solution. Let us make a better world for our industry!



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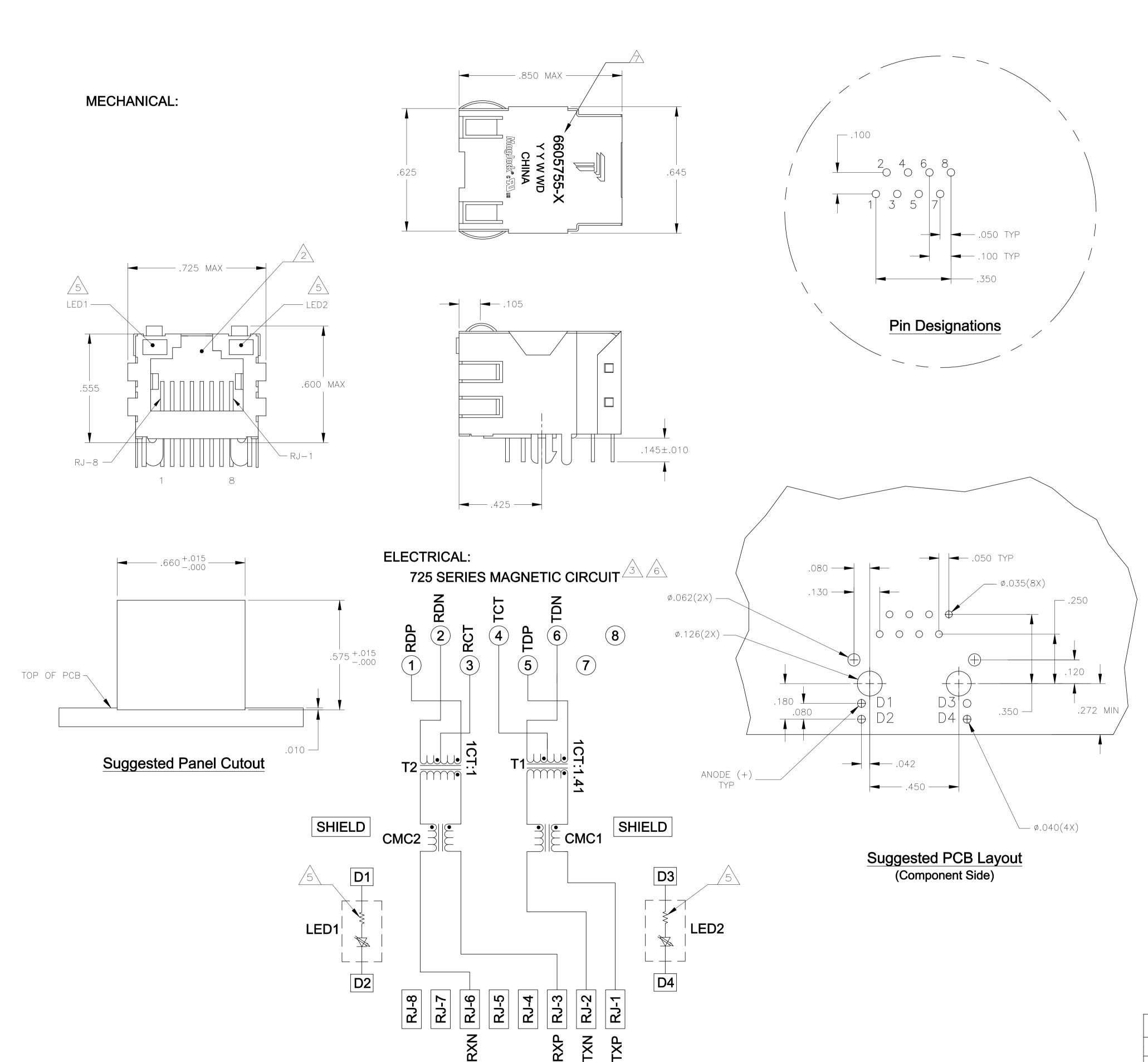
TRP Connector

PRODUCT MAY BE PROTECTED BY ONE OR MORE OF THE FOLLOWING US PATENTS: 5736910 5939955 6425781 6428361 6554638 6840817 7123117 7429195 7717749 7808751 6217391 6149050 7924130

REVISIONS

LTR DESCRIPTION DATE DWN APVD

E EC-1411035 COMPANY LOGO CHANGE 05JAN2015 HY KZ



MATERIALS:

-HOUSING - THERMOPLASTIC PET POLYESTER FLAMMABILITY RATING UL 94V-0.

-SHIELD - .010" THICK, C26800 BRASS PREPLATED WITH 30μINCH MIN SEMI-BRIGHT NICKEL, SOLDER TABS POST DIPPED WITH 100μINCH MIN SAC SOLDER.

-MOD JACK CONTACTS - 0.0157" × 0.018" PHOSPHOR BRONZE, 50μINCH MIN OVERALL NICKEL UNDERPLATE, WITH SELECT 50μINCH MIN HARD GOLD FINISH PLATE.

SOLDERTAILS WITH 100μINCH MIN MATTE TIN AND/OR SAC SOLDER DIP.

-LIGHT EMITTING DIODE(LED) - DIFFUSED EPOXY LENS, .020" × .020" CARBON STEEL WIREFRAME LEADS PRE-PLATED WITH 80μINCH SILVER OVER 40μINCH NICKEL UNDERPLATE OVER 40μINCH COPPER UNDERPLATE, POST-PLATED WITH 100μINCH MIN MATTE TIN AND/OR SAC SOLDER DIP OR PURE TIN SOLDER DIP.

RJ45 JACK CAVITY CONFORMS TO FCC RULES AND REGULATIONS PART 68, SUB PART F.

MAGNETICS
-APPLICATION: 10 BASE-T
-IMPEDANCE: 100 OHMS
-TURNS RATIO (CHIP:CABLE): TX = 1:1.41 RX = 1:1
-TRANSMIT OPEN CIRCUIT INDUCTANCE (OCL): 140μH MIN @ 100kHz, 0.1VRMS
-LEAKAGE INDUCTANCE (LL): 0.40μH MAX @ 100kHz, 0.1VRMS
-INTERWINDING CAPACITANCE (CWW): 12pF MAX @ 100kHz, 0.1VRMS
-ISOLATION VOLTAGE:1500VAC (MAX) AT 60Hz FOR 60 SECS.

4. OPERATING TEMPERATURE: FROM 0° TO +70°C.

IF THE LED WITH 250 OHM RESISTORS, LED IS DRIVEN WITH 5V VOLTAGE AND THE MAX OPERATING CURRENT IS 20mA.

LED COLOR: DOMINANT WAVELENGTH (λD): GREEN 568 nm TYP. @ VF=5V

FORWARD CURRENT (IF): GREEN 12 mA TYP. @ VF=5V

DOMINANT WAVELENGTH (λD): YELLOW 588 nm TYP. @ VF=5V

FORWARD CURRENT (IF): YELLOW 13 mA TYP. @ VF=5V

A INDICATED CONNECTIONS ARE FOR NIC CONFIGURATION.

TRP CONNECTOR LOGO, PART NUMBER, DATE CODE, COUNTRY OF ORIGIN AND AGENCY APPROVAL MARKING IN APPROXIMATE LOCATION SHOWN.

8. THESE PARTS ARE RECOMMENDED FOR WAVE SOLDERING PROCESS, PREHEAT TEMPERATURE IS 120°C TO 160°C, 120 SECONDS TO 180 SECONDS, PEAK WAVE SOLDERING TEMPERATURE IS 260°C MAX, 10 SECONDS MAX.

OBSOLETE GREEN GREEN 1-6605755-1 GREEN YELLOW 6605755-LED2/5 PART NUMBER THIS DRAWING IS A CONTROLLED DOCUMENT. DONGGUAN CHINA ± -± -± .010 ± .005 ± -MAGJACK SINGLE RESTRICTED NON-POE 108-2100 CUSTOMER DRAWING